# Nch 45V 20A Power MOSFET

$V_{DSS}$	45V
R <sub>DS(on)</sub> (Max.)	28mΩ
I <sub>D</sub>	±20A
P <sub>D</sub>	20W

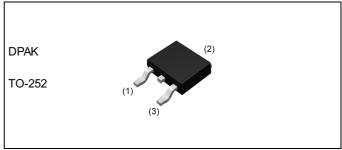
# ● Features

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating; RoHS compliant

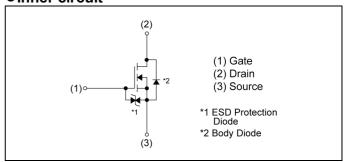
# Application

Switching

### Outline



# ●Inner circuit



Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
	Basic ordering unit (pcs)	2500
	Taning and	TL
	Taping code	TL1
	Marking	RD3H200SN

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	45	V
Continuous drain current	I <sub>D</sub> *1	±20	Α
Pulsed drain current	I <sub>DP</sub> *2	±40	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Power dissipation	P <sub>D</sub> *3	20	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Parameter	Cymhal	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *3	-	ı	6.25	°C/W

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Parameter Symbol Conditions		Values			Unit
Parameter			Min.	Тур.	Max.	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	45	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	46.8	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 45V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate - Source leakage current I <sub>GSS</sub> V <sub>0</sub>		$V_{GS} = \pm 20V, V_{DS} = 0V$	-	1	±10	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{D} = 1mA$	1.0	1	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.9	-	mV/°C
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	20	28	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	25	35	mΩ
		V <sub>GS</sub> = 4V, I <sub>D</sub> = 20A	-	28	40	
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	5.3	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *4	$V_{DS} = 10V, I_{D} = 20A$	10	1	-	S

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw $\leq$ 10 $\mu$ s , Duty cycle $\leq$ 1%

<sup>\*3</sup> T<sub>C</sub>=25°C

<sup>\*4</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymahal	Conditions	Values			l leit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	950	-	_
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	-	250	-	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	120	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 25V, V_{GS} = 10V$	-	10	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 10A	-	20	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 2.5\Omega$		50	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	20	-	

# ●Gate charge characteristics (T<sub>a</sub> = 25°C)

<u> </u>	\ u	,				
Parameter	Symbol	Conditions		Values		Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg*4	V <sub>DD</sub> ≃ 25V.	-	12	-	
Gate - Source charge	Q <sub>gs</sub> *4	$V_{DD} \approx 25V$ , $I_D = 20A$ , $V_{GS} = 5V$	-	3.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4		-	4.0	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	I <sub>S</sub> *1	T - 25°C	-	-	16	Α	
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	40	Α	
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

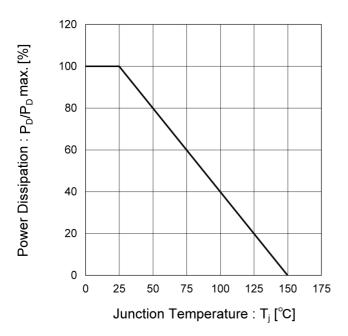


Fig.2 Maximum Safe Operating Area

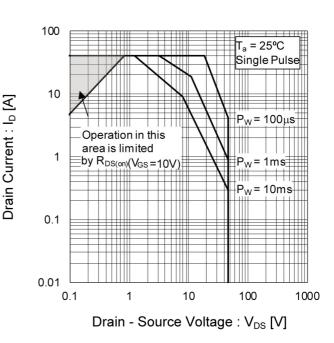


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

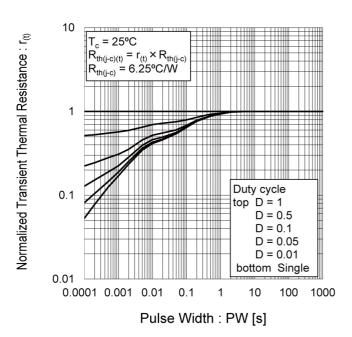


Fig.4 Single Pulse Maximum Power dissipation

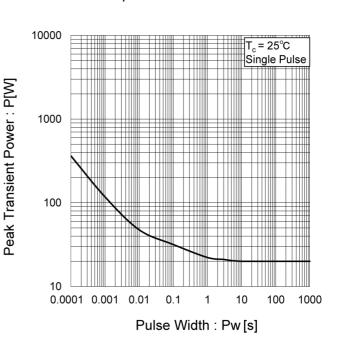


Fig.5 Typical Output Characteristics(I)

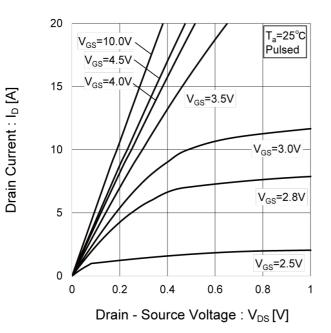
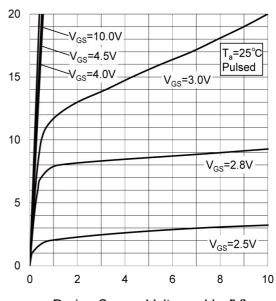
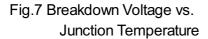


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]



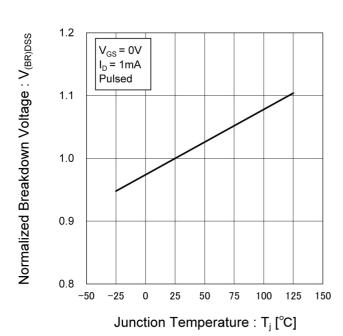


Fig.8 Typical Transfer Characteristics

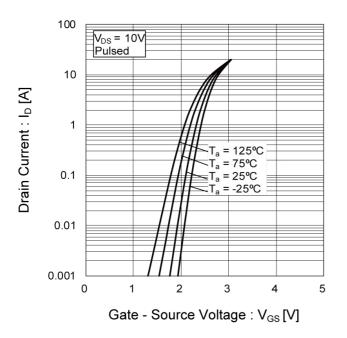


Fig.9 Gate Threshold Voltage vs.

Junction Temperature

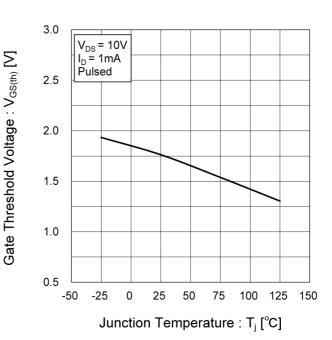


Fig.10 Forward Transfer Admittance vs.
Drain Current

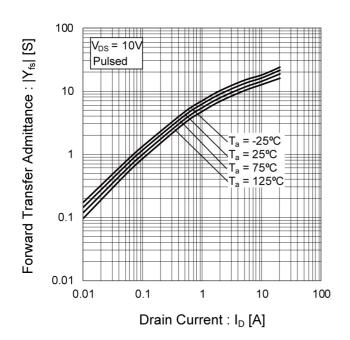


Fig.11 Drain Current Derating Curve

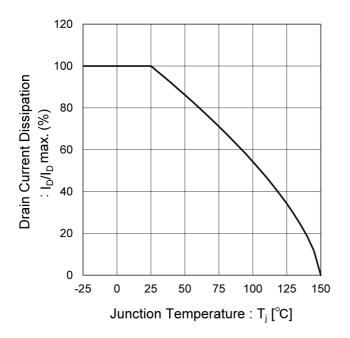


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

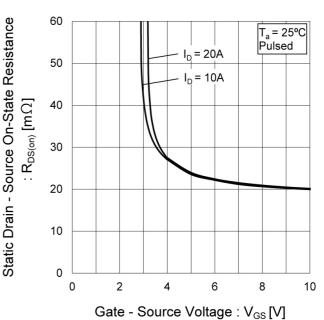


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

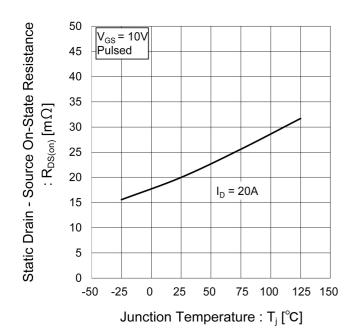


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

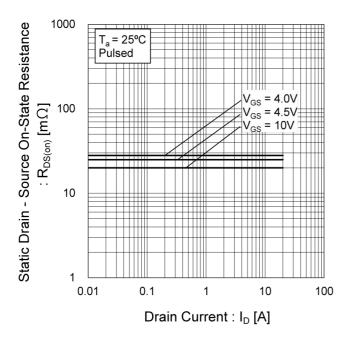


Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current(II)

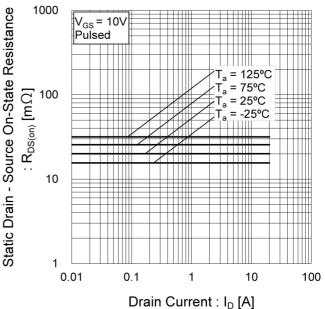


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

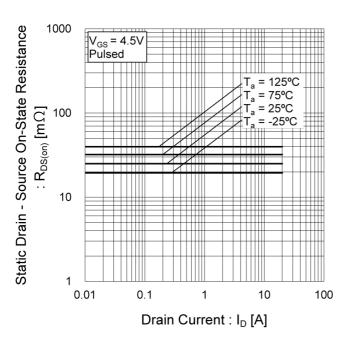


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

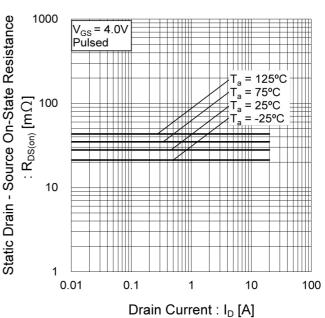


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

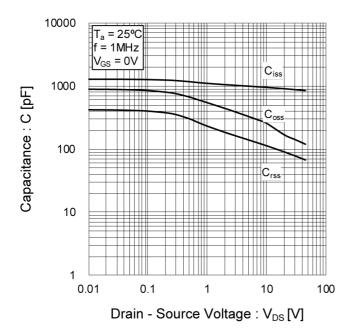


Fig.19 Switching Characteristics

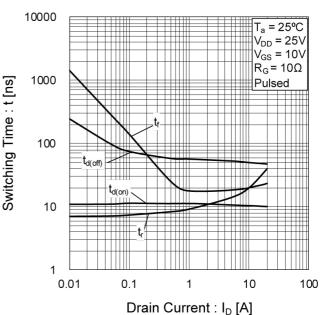


Fig.20 Dynamic Input Characteristics

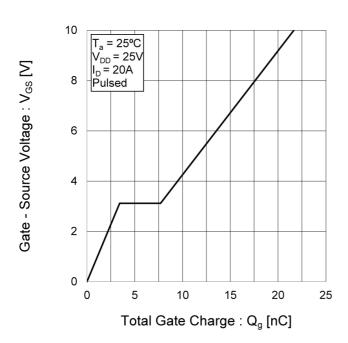
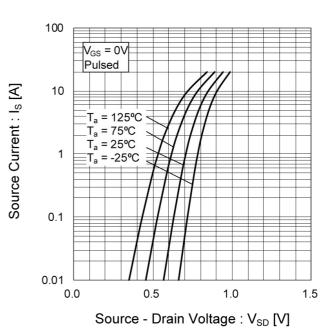


Fig.21 Source Current vs.

Source Drain Voltage



### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

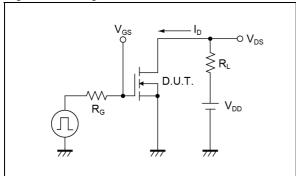


Fig.2-1 Gate Charge Measurement Circuit

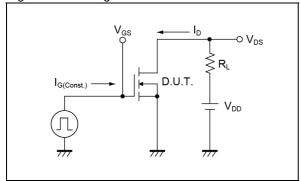


Fig.1-2 Switching Waveforms

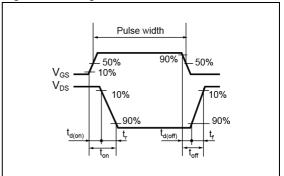
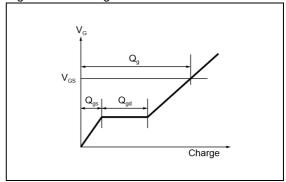
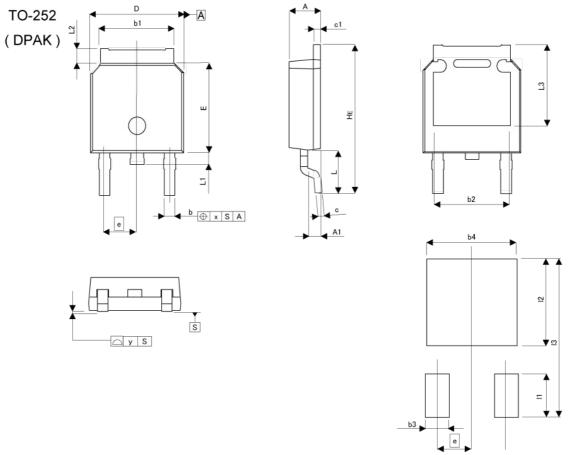


Fig.2-2 Gate Charge Waveform



# ullet Dimensions (TL)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

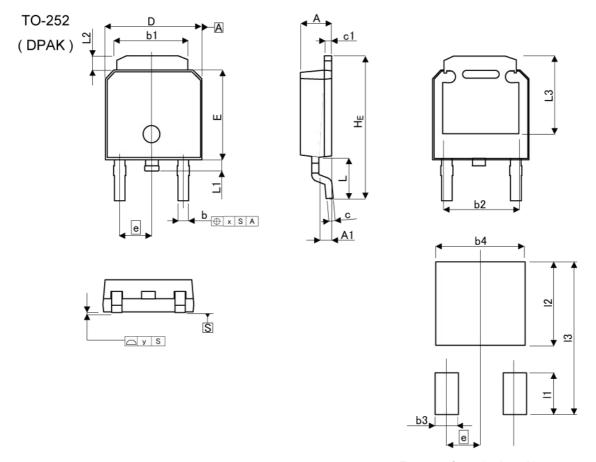
DIM	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
H⊨	9.50	10.50	0.374	0.413
L	2.	90	0.1	14
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	209
Х	-	0.10	(/a)	0.004
у	-	0.10	-	0.004

	DIM	MILIME	MILIMETERS		HES
		MIN	MAX	MIN	MAX
	b3	-	1.10	020	0.043
	b4	-	5.40	2. <b>-</b> 3	0.213
	I1	2	2.90	-	0.114
	12	-	5.50	11-11	0.217
	13	-	10.50	72	0.413

Dimension in mm/inches



# ● Dimensions (TL1)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	189
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.30		0.091	
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
Х	-	0.25	-	0.010
у	-	0.10	-	0.004
D.11.4	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b3	-	1.15		0.045
b4	-	5.55	(. <del></del> )	0.219
I1	-	2.77	(=)	0.109
12	-	5.50	.=.:	0.217
13	-	10.40	-	0.409

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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